NOTES

Allow clearance for finger squeeze access from the two sides shown.

No tracks or vias in the shaded keepout area.

No other track or signal within 0.020" of any contact pad.

Do not allow solder paste on the contact pads. It is essential to eliminate any hole in the solder paste—mask (solder stencil) layer. If this is not possible make the contact pads thru-hole with finished hole size of 0.008" or less.

Leg and alignment holes may be plated and used as vias but ensure minimum finished hole size meets specified tolerances.

To prevent purchasing confusion, please specify DNL in your BOM!

Microchip ICD / ICSP SIGNALS
Pin 1: -MCLR/Vpp
Pin 2: Vdd
Pin 3: Ground
Pin 4: PGD (ICSPDAT)
Pin 5: PGC (ICSPCLK)
Pin 6: Unused or LVP

Allow finger access from this side

Allow finger access from this side

TRACING AND VIA "KEEP OUT" AREA ADDITIONALLY NO VIAS WITHIN 0.020" OF ANY CONTACT PAD

3X ø0.039±0.003 NON-PLATED THRU ALIGNMENT PIN HOLES

6X ø0.031±0.003 CONDUCTIVE CONTACT PAD NO SOLDER PASTE!!!

4X ø0.0935±0.003 NON-PLATED THRU LEG LATCH HOLES